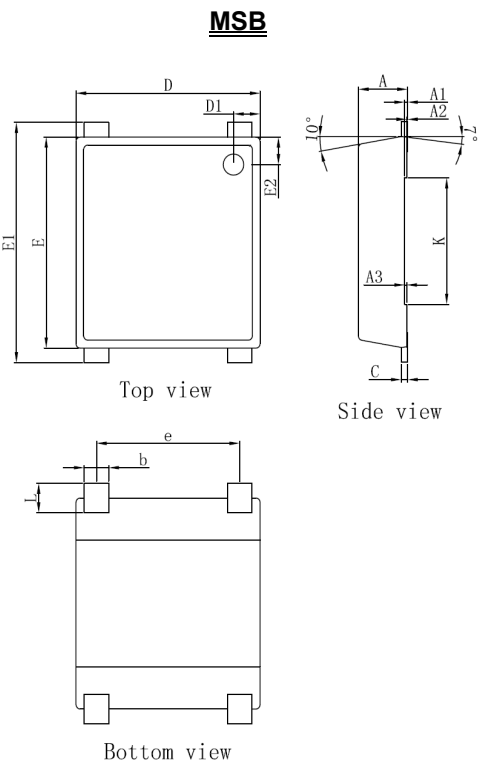


Package Dimension :



| MSB | | | |
|------------------------------|------|------|------|
| Dim. | Min. | Typ. | Max. |
| A | 1.10 | 1.20 | 1.30 |
| A1 | 0.05 | --- | 0.08 |
| A2 | 0.00 | 0.02 | 0.05 |
| A3 | 0.03 | 0.05 | 0.08 |
| C | 0.12 | 0.15 | 0.18 |
| D | 4.40 | 4.5 | 4.60 |
| D1 | 0.60 | 0.65 | 0.70 |
| E | 4.90 | 5.00 | 5.10 |
| E1 | 5.80 | 5.90 | 6.10 |
| E2 | 0.60 | 0.65 | 0.70 |
| L | 0.70 | 0.80 | 1.00 |
| b | 0.55 | 0.60 | 0.70 |
| e | 3.45 | 3.50 | 3.55 |
| K | 2.95 | 3.00 | 3.05 |
| All dimensions in millimeter | | | |

FIG.1-FORWARD CURRENT DERATING CURVE

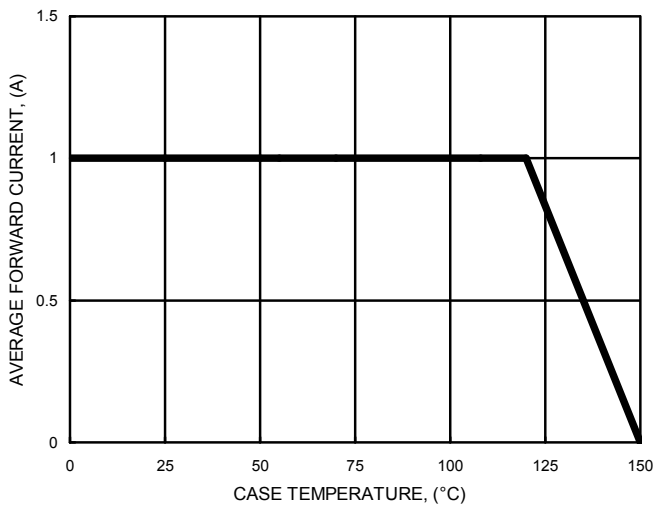


FIG.2- MAXIMUM NON-REPETITIVE SURGE CURRENT

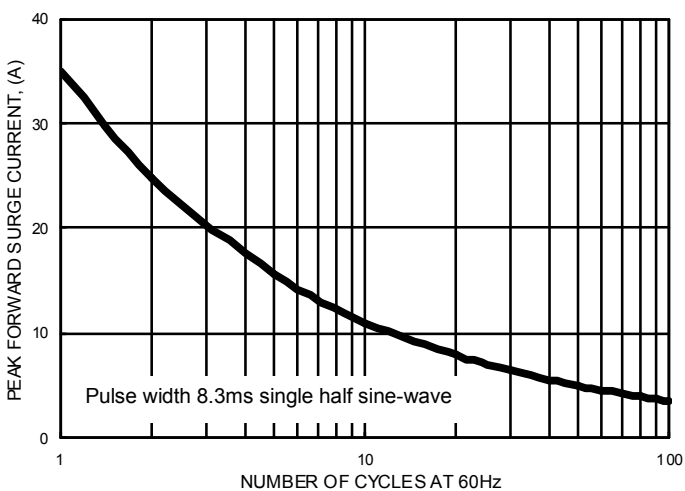


FIG.3- TYPICAL FORWOD CHARACTERISTICS

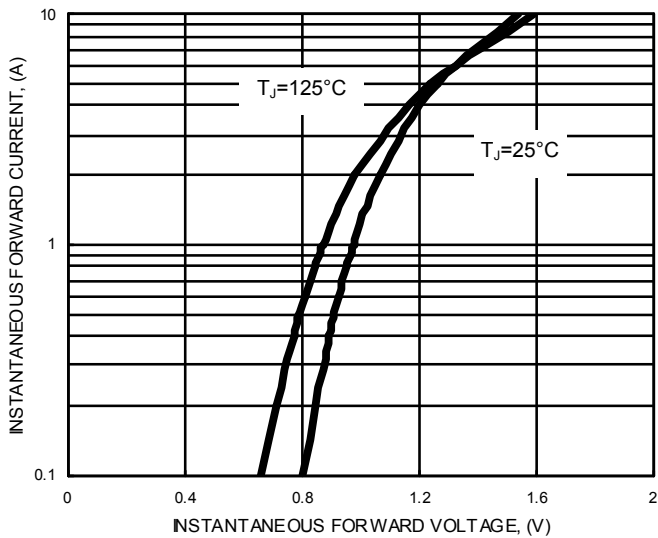


FIG.4- TYPICAL JUNCTION CAPACITANCE

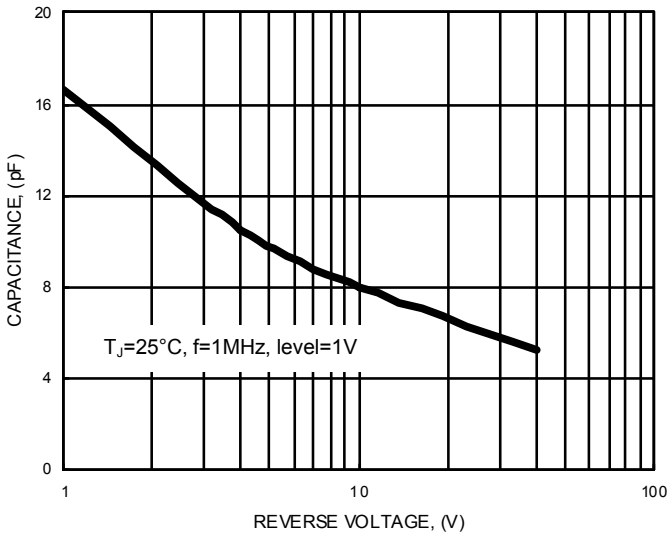
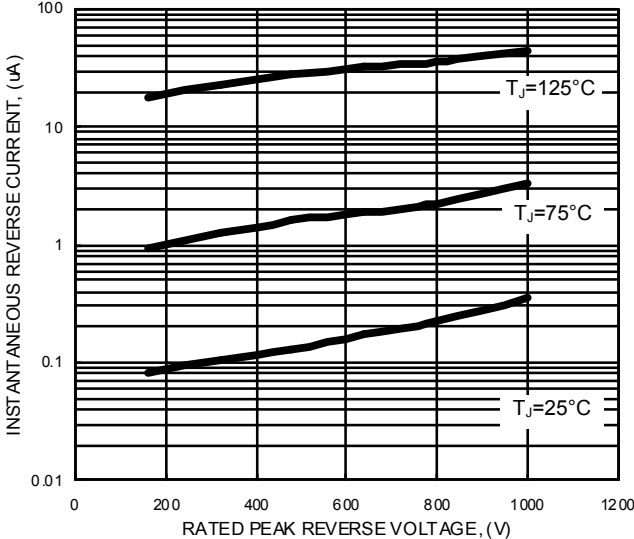
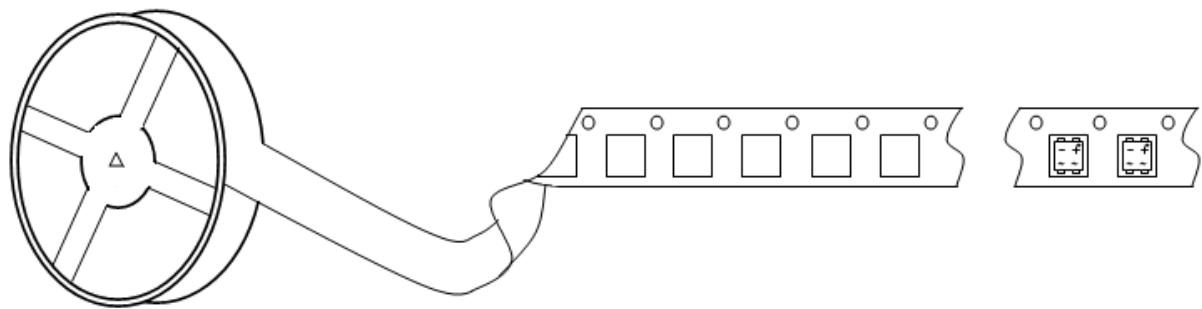


FIG.5- TYPICAL REVERSE CHARACTERISTICS

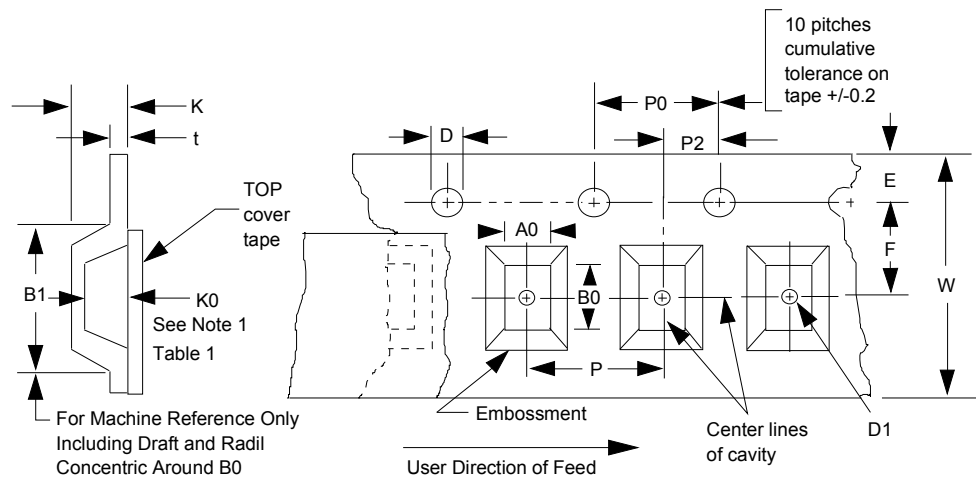


Packaging Information :

| DEVICE | Q'TY/REEL (PCS) | REEL DIA. (mm) | BOX SIZE (mm) | Q'TY/BOX (PCS) | CARTON SIZE (mm) | Q'TY/CARTON (PCS) | MOQ |
|--------|--------------------|-------------------|------------------|-------------------|---------------------|----------------------|-----|
| MSB10M | 3000 | 330 | 334x334x21 | 3000 | 365x365x355 | 36K | 36K |



Embossed Carrier Dimension :



UNIT: mm

| TAPE SIZE | D | E | PO | t (MAX) | A0 | B0 | K0 |
|-----------|----------------|-------------|------------|------------|------------|-------------|-----------|
| 12mm | 1.55+0.10/-0.0 | 1.75+/-0.10 | 4.0+/-0.10 | 0.4 | 4.8+/-0.1 | 6.0+/-0.1 | 1.5+/-0.1 |
| | B1 (MAX) | D1 (MIN) | F | K (MAX) | P2 | W | P |
| | 8.2 | 1.5 | 5.5+/-0.1 | 2.2 | 2.0+/-0.05 | 12.0+/-0.30 | 8.0+/-0.1 |

Typical IR Reflow Soldering Thermal Profile :

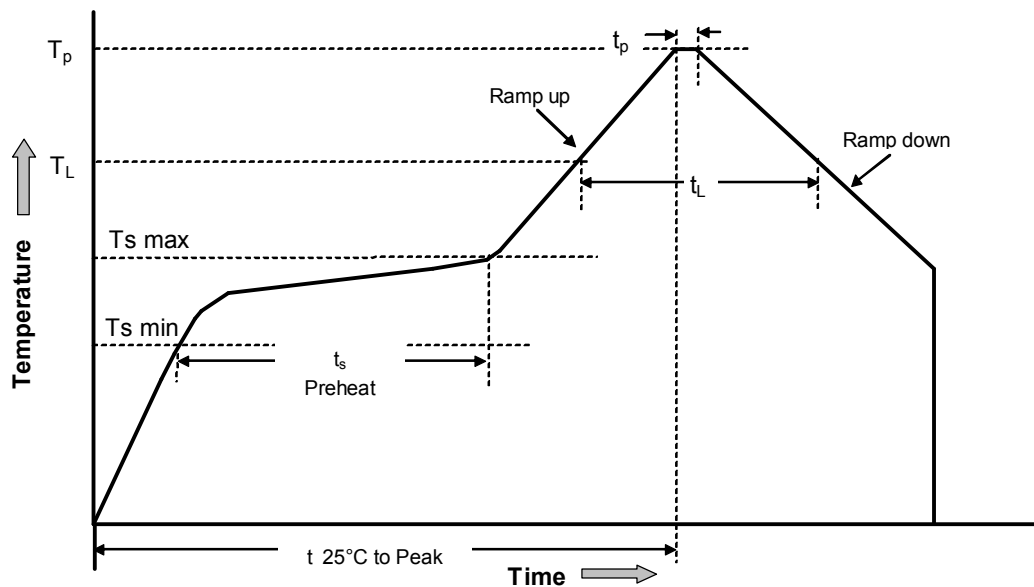


Table 1- Reflow profile

| Reflow condition | Sn-Pb assembly | Pb-free assembly |
|--|------------------|------------------|
| Average ramp-up rate (Liquidus Temperature (TL) to Peak) | 3 °C/second max. | 3 °C/second max. |
| Preheat | | |
| --Temperature Min, Ts (Min) | 100 °C | 150 °C |
| --Temperature Max, Ts (Max) | 150 °C | 200 °C |
| --Time (min to max, ts) | 60-120 seconds | 60-180 seconds |
| Ts(max) to TL | | 3 °C/second max. |
| - Ramp-up Rate | | |
| Time maintained above: | | |
| --Temperature(TL) | 183 °C | 217 °C |
| --Time(tL) | 60-150 seconds | 60-150 seconds |
| Peak Temperature (Tp) | 240 +0/-5 °C | 260 +0/-5 °C |
| Time within 5 °C of actual Peak Temperature(tp) | 10-30 seconds | 20-40 seconds |
| Ramp-down Rate | 6 °C/second max. | 6 °C/second max. |
| Time 25 °C to Peak Temperature. | 6 minutes max. | 8 minutes max. |

Note: All temperatures refer to topside of the package, measured on the package body surface

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